

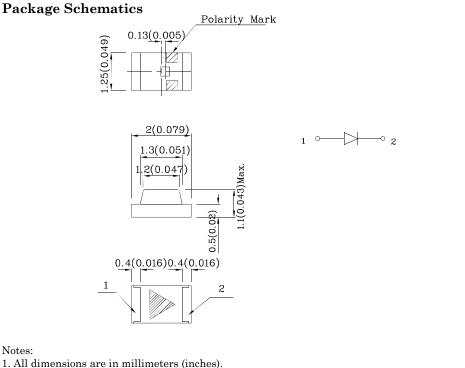
Part Number: XZTNI54W

2.0x1.25mm INFRARED EMITTING DIODE

Features

- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- \bullet RoHS compliant





2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

3. Specifications are subject to	o change without notice.
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Absolute Maximum Ratings (T _A =25°C)		Infrared (GaAs)	Unit
Reverse Voltage	verse Voltage V _R		V
Forward Current	$I_{\rm F}$	50	mA
Forward Current (Peak) 1/100 Duty Cycle 10us Pulse Width	ifs	1200	mA
Power Dissipation	$\mathbf{P}_{\mathbf{D}}$	80	mW
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	C

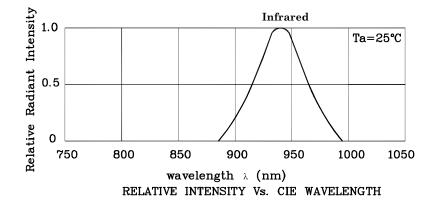
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

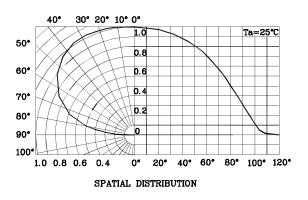
Operating Characteristics (T _A =25°C)		Infrared (GaAs)	Unit
Forward Voltage (Typ.) (I _F =20mA)	VF	1.2	V
Forward Voltage (Max.) (I _F =20mA)	VF	1.6	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	940*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle \lambda$	50	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	90	$_{\rm pF}$

Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* (Po=mW/sr) @20mA		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
			min.	typ.		
XZTNI54W	GaAs	Water Clear	1.2 0.8*	2.8 1.8*	940*	160°

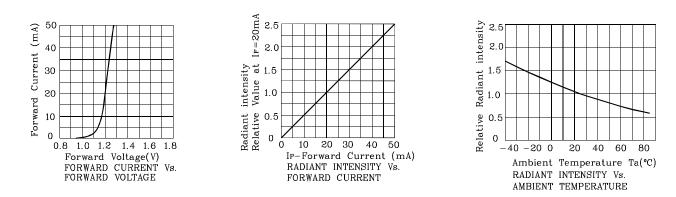
*Radiant Intensity value and wavelength are in accordance with CIE127-2007 standards.

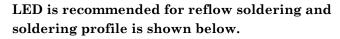






Infrared





300 (°C) 10 s max 250 4°C/s C/s max 200 150-180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Tim Notes:

Reflow Soldering Profile for SMD Products (Pb-Free Components)

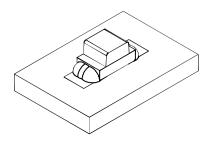
1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

high temperatures conditions



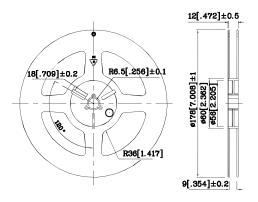
The device has a single mounting surface. The device must be mounted according to the specifications.



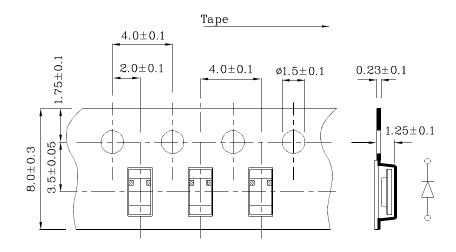
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage or radiant intensity / luminous flux),

the typical accuracy of the sorting process is as follows:

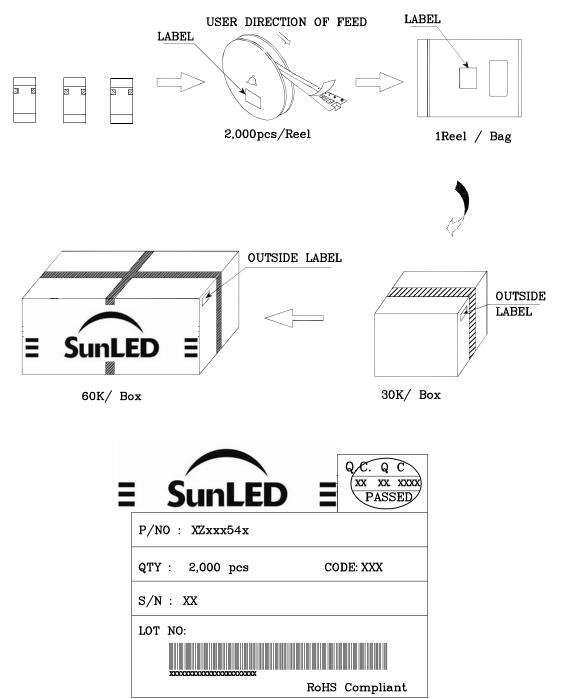
1. Radiant Intensity / Luminous Flux: +/-15%

2. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

Oct 11,2016